

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : [CL31A475KACLNNC](#)
- Descriptionnt : [CAP, 4.7 \$\mu\$ F, 25V, \$\pm\$ 10%, X5R, 1206](#)

A. Samsung Part Number

CL 31 A 475 K A C L N N C
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	1206 (inch code)	L: 3.2 $\pm$ 0.2 mm	W: 1.6 $\pm$ 0.2 mm							
③ Dielectric	X5R	⑧ Thickness division		Low profile						
④ Capacitance	4.7 μ F	Inner electrode		Ni						
⑤ Capacitance tolerance	$\pm$ 10 %	Termination		Cu						
⑥ Rated Voltage	25 V	Plating		Sn 100% (Pb Free)						
⑦ Thickness	0.85 $\pm$ 0.1 mm	⑨ Product		Normal						
		⑩ Special		Reserved for future use						
		⑪ Packaging		Cardboard Type, 7"reel(4,000ea)						

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz $\pm$ 10% 1.0 $\pm$ 0.2Vrms
Tan δ (DF)	0.1 max.	
Insulation Resistance	More than 100Mohm $\cdot\mu$ F	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Visual inspection
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characteristics	X5R (From -55 $^{\circ}$ C to 85 $^{\circ}$ C, Capacitance change should be within $\pm$ 15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10 $\pm$ 1 sec.
Bending Strength	Capacitance change : within $\pm$ 12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 $\pm$ 5 $^{\circ}$ C, 3 $\pm$ 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within $\pm$ 7.5% Tan δ , IR : initial spec.	Solder pot : 270 $\pm$ 5 $^{\circ}$ C, 10 $\pm$ 1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.125 max IR : More than 12.5M $\Omega \cdot \mu F$	With rated voltage 40 $\pm 2^{\circ}C$, 90~95%RH, 500 +12/-0 hour
High Temperature Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.125 max IR : More than 25M $\Omega \cdot \mu F$	With 150% of the rated voltage Max. operating temperature 1000+48/-0 hour
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^{\circ}C$ $\rightarrow$ Max. operating temperature $\rightarrow 25^{\circ}C$ 5 cycles test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}C$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.